



Semiconductor CMP Pad Technology Company NexPlanar Achieves ISO 9001:2000 Certification

NexPlanar customizes CMP pads for specific applications; installs QMS (Quality Management System) for customer satisfaction

Hillsboro, Oregon, February 26, 2009

NexPlanar, the semiconductor CMP pad technology company, has achieved ISO 9001:2000 certification, a designation demonstrating the organization's commitment to quality-of-service standards. NexPlanar received its certification on February 11 from United Registrar Services, an accredited independent auditing firm, for meeting guidelines set out by the [International Organization for Standardization](#) (ISO).

CMP Pads

NexPlanar uses proprietary "nano-domain" technology which improves planarity and across wafer uniformity and can be utilized to customize the CMP pads for specific applications. The application specific CMP pads can be tuned, for example, for sensitive structures on the device by varying the hard and soft domains of the pad. NexPlanar's "nano-lubricants" and patented molded groove technologies allow for low stress CMP (required for the most advanced CMP applications), result in an order of magnitude fewer defects, and allow the use of low slurry consumption processing. Significant evaluation and qualification activity is underway at major semiconductor manufacturers on a global basis for oxide, STI and copper CMP applications.

The certificate confirms that NexPlanar's internal quality management system complies with ISO 9001:2000 requirements. Recognized in more than 150 countries, the ISO 9001:2000 standard places a strong emphasis on customer satisfaction, management responsibility, continual improvement, and organizational performance measurement.

Quality Management System

The ISO 9001:2000 standard specifies Quality Management System (QMS) requirements focused on an organization's ability to meet and improve upon customer satisfaction and quality requirements. As part of the certification process, NexPlanar established its own QMS to ensure that the company's customer support organization continued its long-standing commitment to customer satisfaction.

The company manufactures in Hopkins, Minnesota and at its new headquarters in Hillsboro, Oregon.

About NexPlanar Corporation

NexPlanar builds the next generation of chemical mechanical planarization (CMP) pads for the semiconductor device industry. Their proprietary nano-domain technology coupled with patented molded grooves and the unique ability to tune the pads results in dramatically improved

planarization capability, low defectivity levels and lower overall cost of ownership. See <http://www.nexplanar.com>.

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